# MICROCHIP MCP1825/MCP1825S

# 500 mA, Low Voltage, Low Quiescent Current LDO Regulator

#### Features

- 500 mA Output Current Capability
- Input Operating Voltage Range: 2.1V to 6.0V
- Adjustable Output Voltage Range: 0.8V to 5.0V (MCP1825 only)
- Standard Fixed Output Voltages:
  - 0.8V, 1.2V, 1.8V, 2.5V, 3.0V, 3.3V, 5.0V
- Other Fixed Output Voltage Options Available
   Upon Request
- Low Dropout Voltage: 210 mV Typical at 500 mA
- Typical Output Voltage Tolerance: 0.5%
- Stable with 1.0 µF Ceramic Output Capacitor
- Fast response to Load Transients
- Low Supply Current: 120 µA (typical)
- Low Shutdown Supply Current: 0.1 µA (typical) (MCP1825 only)
- Fixed Delay on Power Good Output (MCP1825 only)
- Short Circuit Current Limiting and Overtemperature Protection
- TO-263-5 (DDPAK-5), TO-220-5, SOT-223-5 Package Options (MCP1825).
- TO-263-3 (DDPAK-3), TO-220-3, SOT-223-3 Package Options (MCP1825S).

#### **Applications**

- High-Speed Driver Chipset Power
- Networking Backplane Cards
- Notebook Computers
- Network Interface Cards
- Palmtop Computers
- 2.5V to 1.XV Regulators

#### Description

The MCP1825/MCP1825S is a 500 mA Low Dropout (LDO) linear regulator that provides high current and low output voltages. The MCP1825 comes in a fixed or adjustable output voltage version, with an output voltage range of 0.8V to 5.0V. The 500 mA output current capability, combined with the low output voltage capability, make the MCP1825 a good choice for new sub-1.8V output voltage LDO applications that have high current demands. The MCP1825S is a 3-pin fixed voltage version.

The MCP1825/MCP1825S is stable using ceramic output capacitors that inherently provide lower output noise and reduce the size and cost of the entire regulator solution. Only 1  $\mu$ F of output capacitance is needed to stabilize the LDO.

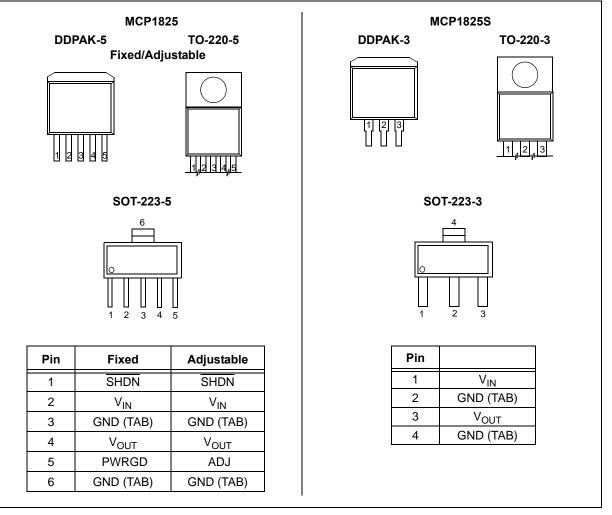
Using CMOS construction, the quiescent current consumed by the MCP1825/MCP1825S is typically less than 120  $\mu$ A over the entire input voltage range, making it attractive for portable computing applications that demand high output current. The MCP1825 versions have a Shutdown (SHDN) pin. When shut down, the quiescent current is reduced to less than 0.1  $\mu$ A.

On the MCP1825 fixed output versions, the scaleddown output voltage is internally monitored and a power good (PWRGD) output is provided when the output is within 92% of regulation (typical). The PWRGD delay is internally fixed at 110 µs (typical).

The overtemperature and short circuit current-limiting provide additional protection for the LDO during system fault conditions.

# MCP1825/MCP1825S

#### Package Types



#### 1.0 ELECTRICAL **CHARACTERISTICS**

#### Absolute Maximum Ratings †

V <sub>IN</sub>
Maximum Voltage on Any Pin (GND – 0.3V) to $(V_{DD}$ + 0.3)V
Maximum Power Dissipation Internally-Limited (Note 6)
Output Short Circuit Duration Continuous
Storage temperature65°C to +150°C
Maximum Junction Temperature, T <sub>J</sub> +150°C
ESD protection on all pins (HBM/MM) $\geq 4 \text{ kV}; \geq 300 \text{ V}$

#### AC/DC CHARACTERISTICS

**† Notice:** Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Electrical Specifications: Unless otherwise noted, $V_{IN} = V_{OUT(MAX)} + V_{DROPOUT(MAX)}$ , Note 1, $V_R = 1.8V$ for Adjustable Output,
$I_{OUT} = 1 \text{ mA}, C_{IN} = C_{OUT} = 4.7 \mu\text{F} (X7\text{R Ceramic}), T_A = +25^{\circ}\text{C}.$
Boldface type applies for junction temperatures. T <sub>1</sub> (Note 7) of -40°C to +125°C

Parameters	Sym	Min	Тур	Max	Units	Conditions
Input Operating Voltage	V <sub>IN</sub>	2.1		6.0	V	Note 1
Input Quiescent Current	۱ <sub>q</sub>	—	120	220	μA	$I_L = 0 \text{ mA}, V_{OUT} = 0.8 \text{V to}$ 5.0V
Input Quiescent Current for SHDN Mode	ISHDN	—	0.1	3	μA	SHDN = GND
Maximum Output Current	I <sub>OUT</sub>	500	—	—	mA	V <sub>IN</sub> = 2.1V to 6.0V V <sub>R</sub> = 0.8V to 5.0V, <b>Note 1</b>
Line Regulation	ΔV <sub>OUT</sub> / (V <sub>OUT</sub> x ΔV <sub>IN</sub> )	—	±0.05	±0. <b>16</b>	%/V	(Note 1) $\leq$ V <sub>IN</sub> $\leq$ 6V
Load Regulation	$\Delta V_{OUT}/V_{OUT}$	-1.0	±0.5	1.0	%	I <sub>OUT</sub> = 1 mA to 500 mA, ( <b>Note 4</b> )
Output Short Circuit Current	I <sub>OUT_SC</sub>	—	1.2	_	А	$R_{LOAD} < 0.1\Omega$ , Peak Current
Adjust Pin Characteristics (Adj	ustable Output O	nly)				
Adjust Pin Reference Voltage	V <sub>ADJ</sub>	0.402	0.410	0.418	V	$V_{IN} = 2.1V$ to $V_{IN} = 6.0V$ , $I_{OUT} = 1$ mA
Adjust Pin Leakage Current	I <sub>ADJ</sub>	-10	±0.01	+10	nA	$V_{IN} = 6.0V$ , $V_{ADJ} = 0V$ to $6V$
Adjust Temperature Coefficient	TCV <sub>OUT</sub>	_	40	_	ppm/°C	Note 3
Fixed-Output Characteristics (F	ixed Output Only	)				
Voltage Regulation	V <sub>OUT</sub>	V <sub>R</sub> - 2.5%	V <sub>R</sub> ±0.5%	V <sub>R</sub> + 2.5%	V	Note 2

Note 1: The minimum V<sub>IN</sub> must meet two conditions: V<sub>IN</sub>  $\ge$  2.1V and V<sub>IN</sub>  $\ge$  V<sub>OUT(MAX)</sub> + V<sub>DROPOUT(MAX)</sub>.

- $V_R$  is the nominal regulator output voltage for the fixed cases.  $V_R = 1.2V$ , 1.8V, etc.  $V_R$  is the desired set point output 2: voltage for the adjustable cases.  $V_R = V_{ADJ} \cdot ((R_1/R_2)+1)$ . Figure 4-1. TCV<sub>OUT</sub> =  $(V_{OUT-HIGH} - V_{OUT-LOW}) *10^6 / (V_R * \Delta Temperature)$ .  $V_{OUT-HIGH}$  is the highest voltage measured over the
- 3: temperature range. V<sub>OUT-LOW</sub> is the lowest voltage measured over the temperature range.

Load regulation is measured at a constant junction temperature using low duty-cycle pulse testing. Load regulation is 4: tested over a load range from 1 mA to the maximum specified output current.

- Dropout voltage is defined as the input-to-output voltage differential at which the output voltage drops 2% below its 5: nominal value that was measured with an input voltage of  $V_{IN} = V_{OUT(MAX)} + V_{DROPOUT(MAX)}$ .
- The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction 6: temperature and the thermal resistance from junction to air. (i.e.,  $T_A$ ,  $T_J$ ,  $\theta_{JA}$ ). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +150°C rating. Sustained junction temperatures above 150°C can impact device reliability.
- The junction temperature is approximated by soaking the device under test at an ambient temperature equal to the 7: desired junction temperature. The test time is small enough such that the rise in the junction temperature over the ambient temperature is not significant.

# AC/DC CHARACTERISTICS (CONTINUED)

**Electrical Specifications:** Unless otherwise noted,  $V_{IN} = V_{OUT(MAX)} + V_{DROPOUT(MAX)}$ , **Note 1**,  $V_R = 1.8V$  for Adjustable Output,  $I_{OUT} = 1 \text{ mA}$ ,  $C_{IN} = C_{OUT} = 4.7 \mu\text{F}$  (X7R Ceramic),  $T_A = +25^{\circ}\text{C}$ .

Boldface type applies for junction temperatures	s, T <sub>J</sub> ( <b>Note 7</b> ) of <b>-40°C to +125°C</b>
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Parameters	Sym	Min	Тур	Max	Units	Conditions
Dropout Characteristics	•		•	•	-	-
Dropout Voltage	V <sub>DROPOUT</sub>	_	210	350	mV	Note 5, I <sub>OUT</sub> = 500 mA, V <sub>IN(MIN)</sub> = 2.1V
Power Good Characteristics						
PWRGD Input Voltage Operat-	V <sub>PWRGD_VIN</sub>	1.0	—	6.0	V	T <sub>A</sub> = +25°C
ing Range		1.2	—	6.0		$T_A = -40^{\circ}C$ to $+125^{\circ}C$
						For $V_{IN}$ < 2.1V, $I_{SINK}$ = 100 $\mu$ A
PWRGD Threshold Voltage	V <sub>PWRGD_TH</sub>				%V <sub>OUT</sub>	Falling Edge
(Referenced to V <sub>OUT</sub> )		89	92	95		V <sub>OUT</sub> < 2.5V Fixed, V <sub>OUT</sub> = Adj.
		90	92	94		V <sub>OUT</sub> >= 2.5V Fixed
PWRGD Threshold Hysteresis	V <sub>PWRGD_HYS</sub>	1.0	2.0	3.0	%V <sub>OUT</sub>	
PWRGD Output Voltage Low	V <sub>PWRGD_L</sub>	—	0.2	0.4	V	I <sub>PWRGD SINK</sub> = 1.2 mA, ADJ = 0V
PWRGD Leakage	P <sub>WRGD–LK</sub>	_	1		nA	$V_{PWRGD} = V_{IN} = 6.0V$
PWRGD Time Delay	T <sub>PG</sub>		110	—	μs	Rising Edge R <sub>PULLUP</sub> = 10 kΩ
Detect Threshold to PWRGD Active Time Delay	T <sub>VDET-PWRGD</sub>	—	200	—	μs	$V_{OUT} = V_{PWRGD_TH} + 20 \text{ mV}$ to $V_{PWRGD_TH} - 20 \text{ mV}$
Shutdown Input						
Logic High Input	V <sub>SHDN-HIGH</sub>	45	—	—	%V <sub>IN</sub>	$V_{IN} = 2.1V$ to 6.0V
Logic Low Input	V <sub>SHDN-LOW</sub>	_	—	15	%V <sub>IN</sub>	V <sub>IN</sub> = 2.1V to 6.0V
SHDN Input Leakage Current	SHDNILK	-0.1	±0.001	+0.1	μΑ	$\frac{V_{IN} = 6V, \text{ SHDN} = V_{IN},}{\text{SHDN} = \text{GND}}$
AC Performance						
Output Delay From SHDN	T <sub>OR</sub>	_	100	—	μs	$\overline{SHDN} = GND \text{ to } V_{IN},$ $V_{OUT} = GND \text{ to } 95\% V_{R}$
Output Noise	e <sub>N</sub>		2.0	_	µV/√Hz	$\label{eq:lour_lour} \begin{split} I_{OUT} &= 200 \text{ mA, f} = 1 \text{ kHz,} \\ C_{OUT} &= 10  \mu\text{F} \text{ (X7R Ceramic),} \\ V_{OUT} &= 2.5 \text{V} \end{split}$

Note 1: The minimum  $V_{IN}$  must meet two conditions:  $V_{IN} \ge 2.1V$  and  $V_{IN} \ge V_{OUT(MAX)} + V_{DROPOUT(MAX)}$ .

2:  $V_R$  is the nominal regulator output voltage for the fixed cases.  $V_R = 1.2V$ , 1.8V, etc.  $V_R$  is the desired set point output voltage for the adjustable cases.  $V_R = V_{ADJ} * ((R_1/R_2)+1)$ . Figure 4-1.

3: TCV<sub>OUT</sub> = (V<sub>OUT-HIGH</sub> - V<sub>OUT-LOW</sub>) \*10<sup>6</sup> / (V<sub>R</sub> \*  $\Delta$ Temperature). V<sub>OUT-HIGH</sub> is the highest voltage measured over the temperature range. V<sub>OUT-LOW</sub> is the lowest voltage measured over the temperature range.

4: Load regulation is measured at a constant junction temperature using low duty-cycle pulse testing. Load regulation is tested over a load range from 1 mA to the maximum specified output current.

5: Dropout voltage is defined as the input-to-output voltage differential at which the output voltage drops 2% below its nominal value that was measured with an input voltage of  $V_{IN} = V_{OUT(MAX)} + V_{DROPOUT(MAX)}$ .

6: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction to air. (i.e., T<sub>A</sub>, T<sub>J</sub>, θ<sub>JA</sub>). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +150°C rating. Sustained junction temperatures above 150°C can impact device reliability.

7: The junction temperature is approximated by soaking the device under test at an ambient temperature equal to the desired junction temperature. The test time is small enough such that the rise in the junction temperature over the ambient temperature is not significant.

## AC/DC CHARACTERISTICS (CONTINUED)

**Electrical Specifications:** Unless otherwise noted,  $V_{IN} = V_{OUT(MAX)} + V_{DROPOUT(MAX)}$ , **Note 1**,  $V_R = 1.8V$  for Adjustable Output,  $I_{OUT} = 1 \text{ mA}$ ,  $C_{IN} = C_{OUT} = 4.7 \mu F$  (X7R Ceramic),  $T_A = +25^{\circ}C$ . Boldface type applies for junction temperatures. T<sub>1</sub> (Note 7) of -40°C to +125°C

Parameters	Sym	Min	Тур	Max	Units	Conditions
Power Supply Ripple Rejection Ratio	PSRR	_	60	_	dB	$      f = 100 \text{ Hz},  \text{C}_{\text{OUT}} = 4.7  \mu\text{F}, \\       I_{\text{OUT}} = 100  \mu\text{A}, \\       V_{\text{INAC}} = 100  \text{mV}  \text{pk-pk}, \\       C_{\text{IN}} = 0  \mu\text{F} $
Thermal Shutdown Temperature	T <sub>SD</sub>	_	150	—	°C	$I_{OUT}$ = 100 µA, $V_{OUT}$ = 1.8V, $V_{IN}$ = 2.8V
Thermal Shutdown Hysteresis	$\Delta T_{SD}$	_	10	—	°C	$I_{OUT} = 100 \ \mu A, \ V_{OUT} = 1.8 V, \ V_{IN} = 2.8 V$

The minimum  $V_{IN}$  must meet two conditions:  $V_{IN} \ge 2.1V$  and  $V_{IN} \ge V_{OUT(MAX)} + V_{DROPOUT(MAX)}$ . Note 1:

 $V_R$  is the nominal regulator output voltage for the fixed cases.  $V_R = 1.2V$ , 1.8V, etc.  $V_R$  is the desired set point output voltage for the adjustable cases.  $V_R = V_{ADJ} * ((R_1/R_2)+1)$ . Figure 4-1. TCV<sub>OUT</sub> = (V<sub>OUT-HIGH</sub> - V<sub>OUT-LOW</sub>) \*10<sup>6</sup> / ( $V_R$  \*  $\Delta$ Temperature). V<sub>OUT-HIGH</sub> is the highest voltage measured over the 2:

3: temperature range. V<sub>OUT-LOW</sub> is the lowest voltage measured over the temperature range.

4: Load regulation is measured at a constant junction temperature using low duty-cycle pulse testing. Load regulation is tested over a load range from 1 mA to the maximum specified output current.

Dropout voltage is defined as the input-to-output voltage differential at which the output voltage drops 2% below its 5: nominal value that was measured with an input voltage of  $V_{IN} = V_{OUT(MAX)} + V_{DROPOUT(MAX)}$ .

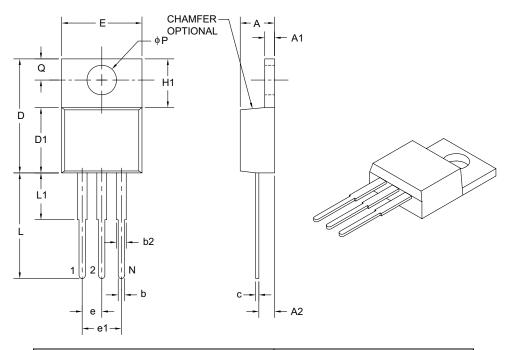
The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction 6: temperature and the thermal resistance from junction to air. (i.e.,  $T_A$ ,  $T_J$ ,  $\theta_{JA}$ ). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +150°C rating. Sustained junction temperatures above 150°C can impact device reliability.

7: The junction temperature is approximated by soaking the device under test at an ambient temperature equal to the desired junction temperature. The test time is small enough such that the rise in the junction temperature over the ambient temperature is not significant.

## **TEMPERATURE SPECIFICATIONS**

Parameters	Sym	Min	Тур	Мах	Units	Conditions	
Temperature Ranges							
Operating Junction Temperature Range	Τ <sub>J</sub>	-40	—	+125	°C	Steady State	
Maximum Junction Temperature	Τ <sub>J</sub>	—	—	+150	°C	Transient	
Storage Temperature Range	T <sub>A</sub>	-65	—	+150	°C		
Thermal Package Resistances							
Thermal Resistance, 3LD DDPAK	$\theta_{JA}$	—	31.4	_	°C/W	4-Layer JC51 Standard	
	$\theta_{JC}$	—	3.0	_		Board	
Thermal Resistance, 3LD TO-220	$\theta_{JA}$	—	29.4		°C/W	4-Layer JC51 Standard Board	
	$\theta_{JC}$	—	2.0	_			
Thermal Resistance, 3LD SOT-223	$\theta_{JA}$	_	62		°C/W	EIA/JEDEC JESD51-751-7	
	$\theta_{JC}$	—	15.0	_		4 Layer Board	
Thermal Resistance, 5LD DDPAK	$\theta_{JA}$	—	31.2	_	°C/W	4-Layer JC51 Standard	
	$\theta_{JC}$	—	3.0	_		Board	
Thermal Resistance, 5LD TO-220	$\theta_{JA}$	_	29.3	_	°C/W	4-Layer JC51 Standard	
	$\theta_{JC}$	—	2.0	_		Board	
Thermal Resistance, 5LD SOT-223	$\theta_{JA}$	—	62		°C/W	EIA/JEDEC JESD51-751-7	
	$\theta_{JC}$	_	15.0	_		4 Layer Board	

#### 3-Lead Plastic Transistor Outline (AB) [TO-220]



	Units	INCHES			
	Dimension Limits	MIN	NOM	MAX	
Number of Pins	N	3			
Pitch	е		.100 BSC		
Overall Pin Pitch	e1		.200 BSC		
Overall Height	A	.140	-	.190	
Tab Thickness	A1	.020	-	.055	
Base to Lead	A2	.080	-	.115	
Overall Width	E	.357	-	.420	
Mounting Hole Center	Q	.100	-	.120	
Overall Length	D	.560	-	.650	
Molded Package Length	D1	.330	-	.355	
Tab Length	H1	.230	-	.270	
Mounting Hole Diameter	φP	.139	-	.156	
Lead Length	L	.500	-	.580	
Lead Shoulder	L1	-	-	.250	
Lead Thickness	С	.012	-	.024	
Lead Width	b	.015	.027	.040	
Shoulder Width	b2	.045	.057	.070	

#### Notes:

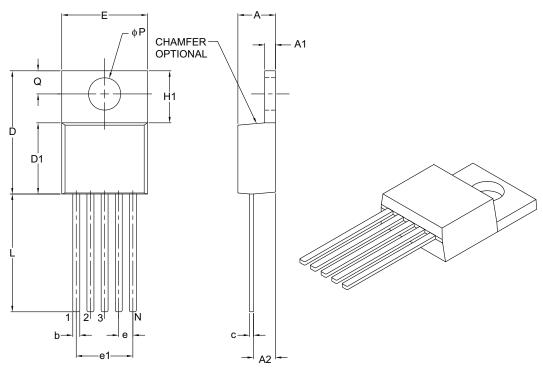
1. Dimensions D and E do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" per side.

2. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-034B

#### 5-Lead Plastic Transistor Outline (AT) [TO-220]



	Units					
	Dimension Limits	MIN	NOM	MAX		
Number of Pins	N	5				
Pitch	е	.067 BSC				
Overall Pin Pitch	e1		.268 BSC			
Overall Height	A	.140	-	.190		
Overall Width	E	.380	-	.420		
Overall Length	D	.560	-	.650		
Molded Package Length	D1	.330	-	.355		
Tab Length	H1	.204	-	.293		
Tab Thickness	A1	.020	-	.055		
Mounting Hole Center	Q	.100	-	.120		
Mounting Hole Diameter	φP	.139	-	.156		
Lead Length	L	.482	-	.590		
Base to Bottom of Lead	A2	.080	-	.115		
Lead Thickness	С	.012	-	.025		
Lead Width	b	.015	.027	.040		

#### Notes:

- 1. Dimensions D and E do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" per side.
- 2. Dimensioning and tolerancing per ASME Y14.5M.
  - BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-036B

#### **PRODUCT IDENTIFICATION SYSTEM**

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO. XX X X X XX			Examples:			
	t Feature Tolerance Temp. Package	a) b) c) d) e) f) g) h)	MCP1825-0802E/XX: 0.8V LDO Regulator MCP1825-1202E/XX: 1.2V LDO Regulator MCP1825-1802E/XX: 1.8V LDO Regulator MCP1825-2502E/XX: 2.5V LDO Regulator MCP1825-3002E/XX: 3.0V LDO Regulator MCP1825-3002E/XX: 3.3V LDO Regulator MCP1825-5002E/XX: 5.0V LDO Regulator MCP1825-ADJE/XX: ADJ LDO Regulator			
Output Voltage *:	08 = 0.8V "Standard" 12 = 1.2V "Standard" 18 = 1.8V "Standard" 25 = 2.5V "Standard" 30 = 3.0V "Standard" 33 = 3.3V "Standard" 50 = 5.0V "Standard" ADJ = Adjustable Output Voltage ** (MCP1825 Only)	a) b) c) d) e) f) g)	MCP1825S-0802E/YY:0.8V LDO Regulator MCP1825S-1202E/YY:1.2V LDO Regulator MCP1825S-1802E/YY:1.8V LDO Regulator MCP1825S-2502E/YY:2.5V LDO Regulator MCP1825S-2502E/YY:3.0V LDO Regulator MCP1825S-3302E/YY:3.3V LDO Regulator MCP1825S-5002E/YY:5.0V LDO Regulator			
Extra Feature Code:	*Contact factory for other output voltage options ** When ADJ is used, the "extra feature code" and "tolerance" columns do not apply. Refer to examples. 0 = Fixed	XX	<ul> <li>AT for 5LD TO-220 package</li> <li>DC for 5LD SOT-223 package</li> <li>ET for 5LD DDPAK package</li> </ul>			
Tolerance: Temperature:	2 = 2.5% (Standard) E = -40°C to +125°C	Yì	<ul> <li>AB for 3LD TO-220 package</li> <li>DB for 3LD SOT-223 package</li> <li>EB for 3LD DDPAK package</li> </ul>			
Package Type:	AB=Plastic Transistor Outline, TO-220, 3-leadAT=Plastic Transistor Outline, TO-220, 5-leadEB=Plastic, DDPAK, 3-leadET=Plastic, DDPAK, 5-leadDB=Plastic Small Transistor Outline, SOT-223, 3-leadDC=Plastic Small Transistor Outline, SOT-223, 5-leadNote:ADJ (Adjustable) only available in 5-lead version.					